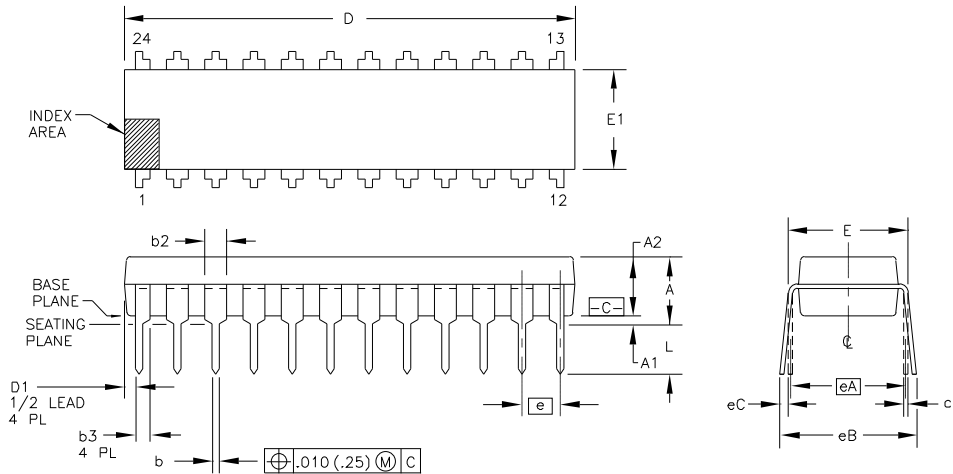


Package Number 243-3 - 24-Pin Plastic, Single-Wide DIP



DIM	INCHES		MILLIMETERS		N O T E	DIM	INCHES		MILLIMETERS		N O T E
	MIN.	MAX.	MIN.	MAX.			MIN.	MAX.	MIN.	MAX.	
A	--	.210	--	5.33	3	eC	.000	.060	0.00	1.52	6
A1	.015	--	0.38	--	3	L	.115	.150	2.92	3.81	3
A2	.115	.195	2.92	4.95		N	24	24			7
b	.014	.022	0.36	0.56							
b2	.045	.070	1.14	1.78	9						
b3	.030	.045	0.76	1.14	9						
c	.008	.014	0.20	0.36							
D	1.160	1.195	29.46	30.35	4						
D1	.005	--	0.13	--	4						
E	.300	.325	7.62	8.26	5						
E1	.240	.280	6.10	7.11	4						
e	.100 BASIC		2.54 BASIC								
eA	.300 BASIC		7.62 BASIC		5						
eB	--	.430	--	10.92	6						

NOTES:

- ALL DIMENSIONS ARE IN INCHES.
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M-1982.
- DIMENSIONS A, A1, AND L ARE MEASURED WITH THE PACKAGE SEATED IN JEDEC SEATING PLANE GAUGE GS-3.
- D, D1, AND E1 DIMENSIONS DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED .010 (0.25mm).
- E AND eA MEASURED WITH THE LEADS CONSTRAINED TO BE PERPENDICULAR TO DATUM $\perp C$.
- eB AND eC ARE MEASURED AT THE LEAD TIPS WITH THE LEADS UNCONSTRAINED.
- N IS THE MAXIMUM OF TERMINAL POSITIONS.

- POINTED OR ROUNDED LEAD TIPS ARE PREFERRED TO EASE INSERTION.
- b2 AND b3 MAXIMUM DIMENSIONS DO NOT INCLUDE DAMBAR PROTRUSIONS. DAMBAR PROTRUSIONS SHALL NOT EXCEED .010 (0.25mm).
- DISTANCE BETWEEN LEADS INCLUDING DAMBAR PROTRUSIONS TO BE .005 (0.13mm) MINIMUM.
- A VISUAL INDEX FEATURE MUST BE LOCATED WITHIN THE CROSS-HATCHED AREA.
- FOR AUTOMATIC INSERTION, ANY RAISED IRREGULARITY ON THE TOP SURFACE (STEP, MESA, ETC.) SHALL BE SYMMETRICAL ABOUT THE LATERAL AND LONGITUDINAL PACKAGE CENTERLINES.

PACKAGE NUMBER: ZZ243-3 REV.: A
 JEDEC NUMBER: MS-001-BE



PACKAGE DRAWING

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